Toshiba Bipolar Digital Integrated Circuit Silicon Monolithic

# TD62081APG,TD62081AFG,TD62082APG,TD62082AFG,TD62083APG,TD62083AFG,TD62084APG,TD62084AFG

### 8ch Darlington Sink Driver

The TD62081APG/AFG Series are high-voltage, high-current darlington drivers comprised of eight NP darlington pairs. All units feature integral clamp diodes for switching inductive loads. Applications include relay, hammer, lamp and display (LED) drivers.

### **Features**

- Output current (single output)
   500 mA (max) (TD62081APG/AFG series)
- High sustaining voltage output
   50 V (min) (TD62081APG/AFG series)
- Output clamp diodes
- Inputs compatible with various types of logic.
- Package type-APG: DIP-18 pin
- Package type-AFG: SOP-18 pin

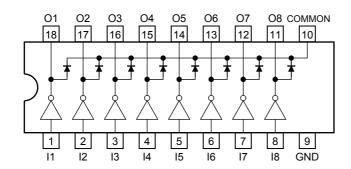
Туре	Input Base Resistor	Designation
TD62081APG/AFG	External	General purpose
TD62082APG/AFG	$\begin{array}{c} 10.5\text{-}k\Omega+7~V\\ \text{Zenner diode} \end{array}$	14 V to 25 V PMOS
TD62083APG/AFG	2.7 kΩ	TTL, 5 V CMOS
TD62084APG/AFG	10.5 kΩ	6 V to 15 V PMOS, CMOS

# DIP18-P-300-2.54D TD62081AFG, TD62082AFG TD62081AFG, TD62082AFG TD62083AFG, TD62084AFG SOP18-P-375-1.27

Weight

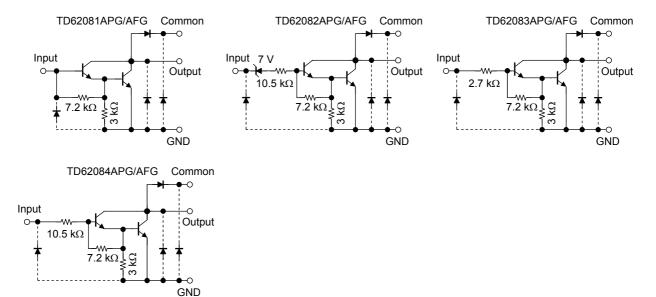
DIP18-P-300-2.54D: 1.47 g (typ.) SOP18-P-375-1.27: 0.41 g (typ.)

### Pin Connection (top view)





### Schematics (each driver)



Note: The input and output parasitic diodes cannot be used as clamp diodes.

### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit	
Output sustaining voltage		V <sub>CE</sub> (SUS)	-0.5 to 50	V	
Output current		lout	500	mA/ch	
Input voltage		V <sub>IN</sub> (Note 1)	-0.5 to 30	V	
Input current		I <sub>IN</sub> (Note 2)	25	mA	
Clamp diode reverse voltage		V <sub>R</sub>	50	٧	
Clamp diode forward current		lF	500	mA	
Power dissipation	APG	PD	1.47	W	
Fower dissipation	AFG	۲۵	0.96	VV	
Operating temperature		T <sub>opr</sub>	-40 to 85	°C	
Storage temperature		T <sub>stg</sub>	-55 to 150	°C	

Note 1: Except TD62081APG/AFG Note 2: Only TD62081APG/AFG



# Recommended Operating Conditions ( $Ta = -40 \text{ to } 85^{\circ}\text{C}$ )

Cha	racteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Output sustaining voltage		V <sub>CE</sub> (SUS)		0	_	50	V
Output current	APG	lout	T <sub>pw</sub> = 25 ms, Duty = 10% 8 circuits	0	_	347	- mA/ch
			T <sub>pw</sub> = 25 ms, Duty = 50% 8 circuits	0	_	123	
	AFG		T <sub>pw</sub> = 25 ms, Duty = 10% 8 circuits	0	_	268	
	AFG		T <sub>pw</sub> = 25 ms, Duty = 50% 8 circuits	0	_	90	
Input voltage	Except TD62081APG/AFG	V <sub>IN</sub>		0	_	30	V
Input voltage (Output on)	TD62082APG/AFG			14	_	30	
	TD62083APG/AFG	V <sub>IN (ON)</sub>		2.5	_	30	٧
( = = = = = = = = = = = = = = = = = = =	TD62084APG/AFG			8	_	30	
	TD62082APG/AFG			0	_	7.4	
Input voltage (Output off)	TD62083APG/AFG	V <sub>IN (OFF)</sub>		0	_	0.5	V
(Gatpat Gil)	TD62084APG/AFG			0	_	1.0	
Input current	Only TD62081APG/AFG	I <sub>IN</sub>		0	_	5	mA
Clamp diode reverse voltage		V <sub>R</sub>		_	_	50	V
Clamp diode forward current		l <sub>F</sub>		_	_	400	mA
Power	APG	P <sub>D</sub>		_	_	0.52	W
dissipation	AFG			_		0.4	VV

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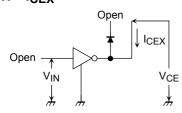
# Electrical Characteristics (Ta = 25°C)

Cha	racteristics	Symbol	Test Circuit	Test Condition		Min	Тур.	Max	Unit
			1	V <sub>CE</sub> = 50 V	Ta = 25°C	_	_	50	- μA
Output leakage					Ta = 85°C	_	_	100	
current	TD62082	I <sub>CEX</sub>			V <sub>IN</sub> = 6 V	_	_	500	
	TD62084				V <sub>IN</sub> = 1 V	_	_	500	
Collector-emitter saturation voltage		V <sub>CE (sat)</sub>	2	$I_{OUT} = 350 \text{ mA}, I_{IN} = 500 \mu\text{A}$		_	1.3	1.6	V
				I <sub>OUT</sub> = 200 mA, I <sub>IN</sub> = 350 μA		_	1.1	1.3	
				I <sub>OUT</sub> = 100 mA, I <sub>IN</sub> = 250 μA		_	0.9	1.1	
	TD62082APG/AFG			V <sub>IN</sub> = 17 V		_	0.82	1.25	
	TD62083APG/AFG			V <sub>IN</sub> = 3.85 V		_	0.93	1.35	mA
Input current	TDC2004ADC/AFC	IN (ON)	2	V <sub>IN</sub> = 5 V		_	0.35	0.5	
	TD62084APG/AFG			V <sub>IN</sub> = 12 V	I <sub>N</sub> = 12 V		1.0	1.45	
		I <sub>IN (OFF)</sub>	4	I <sub>OUT</sub> = 500 μA, Ta = 85°C		50	65	_	μА
	TD62082APG/AFG	Vin (on)		V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 300 mA		_		13	V
	TD62083APG/AFG		5	V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 200 mA		_		2.4	
				V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 250 mA		_		2.7	
Input voltage				V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 300 mA		_		3.0	
(Output on)	TD62084APG/AFG			V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 125 mA		_	_	5.0	
				V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 200 mA		_	_	6.0	
				V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 275 mA		_	_	7.0	
				V <sub>CE</sub> = 2 V, I <sub>OUT</sub> =	350 mA	_	_	8.0	
DC current transfer ratio		h <sub>FE</sub>	2	V <sub>CE</sub> = 2 V, I <sub>OUT</sub> =	350 mA	1000	_	_	
Clamp diode reverse current		I <sub>R</sub>	6	Ta = 25°C	(Note)	_	_	50	
				Ta = 85°C	(Note)	_	_	100	<b>-</b> μ <b>A</b>
Clamp diode forward voltage		VF	7	I <sub>F</sub> = 350 mA		_	_	2.0	V
Input capacitance		C <sub>IN</sub>	_			_	15	_	pF
Turn-on delay		t <sub>OFF</sub> 8		$R_L = 125 \Omega$ , $V_{OUT}$	= 50 V	_	0.1	_	
Turn-off delay				R <sub>L</sub> = 125 Ω, V <sub>OUT</sub> = 50 V		_	0.2	_	μS

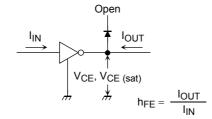
Note:  $V_R = V_R \text{ max}$ 

### **Test Circuit**

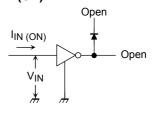
# 1. I<sub>CEX</sub>



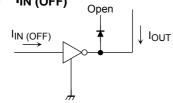
# 2. V<sub>CE (sat)</sub>, h<sub>FE</sub>



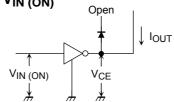
# 3. I<sub>IN (ON)</sub>



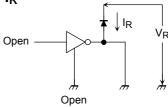
# 4. I<sub>IN (OFF)</sub>

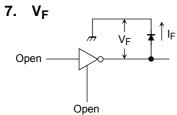


# V<sub>IN (ON)</sub>

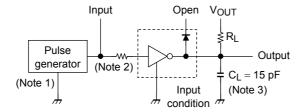


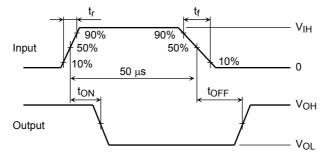
### 6. I<sub>R</sub>





### 8. ton, toff





Note 1: Pulse width 50 µs, duty cycle 10%

Output impedance 50  $\Omega$ ,  $t_f \le 5$  ns,  $t_f \le 10$  ns

Note 2: See below.
Input condition

Type Number	R1	V <sub>IH</sub>
TD62081APG/AFG	2.7 kΩ	3 V
TD62082APG/AFG	0 Ω	13 V
TD62083APG/AFG	0 Ω	3 V
TD62084APG/AFG	0 Ω	8 V

Note 3: C<sub>L</sub> includes probe and jig capacitance

### **Precautions for Using**

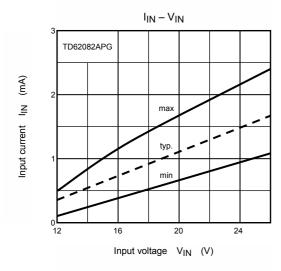
This IC does not include built-in protection circuits for excess current or overvoltage.

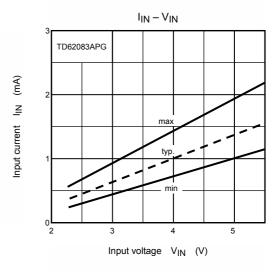
If this IC is subjected to excess current or overvoltage, it may be destroyed.

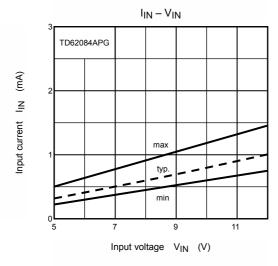
Hence, the utmost care must be taken when systems which incorporate this IC are designed.

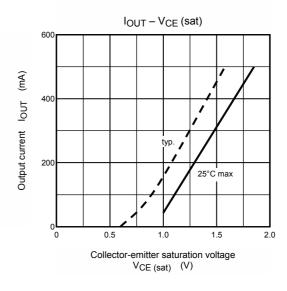
Utmost care is necessary in the design of the output line, COMMON and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

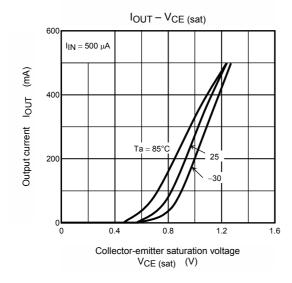
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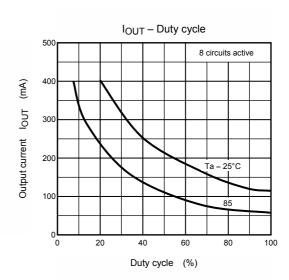


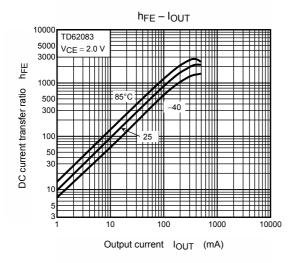


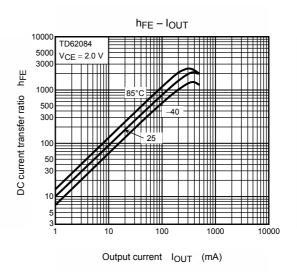


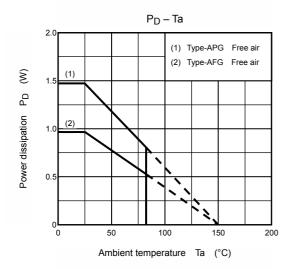








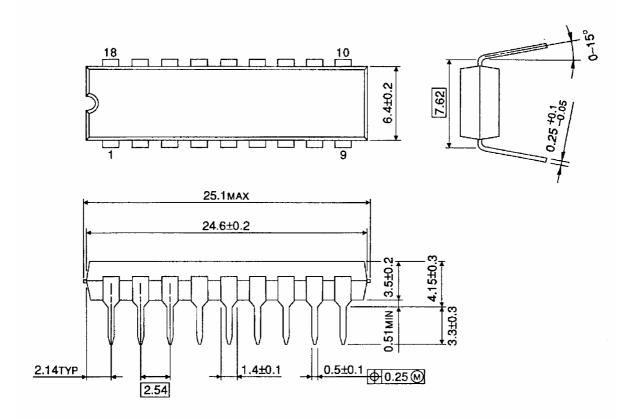




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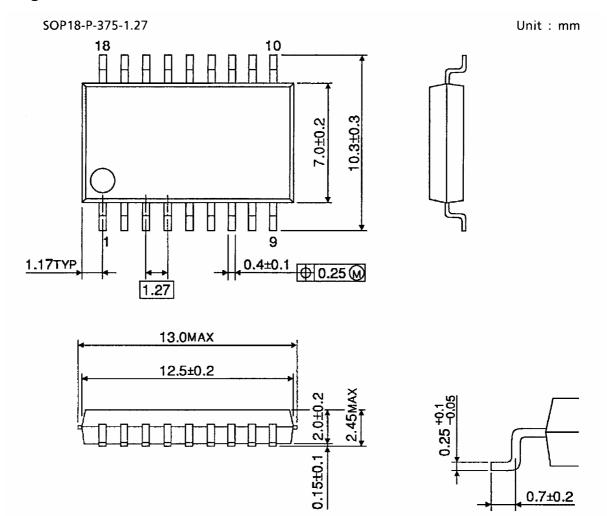
# **Package Dimensions**

DIP18-P-300-2.54D Unit: mm



Weight: 1.47 g (typ.)

# **Package Dimensions**



Weight: 0.41 g (typ.)

About solderability, following conditions were confirmed

- Solderability
- (1) Use of Sn-63Pb solder Bath
  - · solder bath temperature = 230°C
  - · dipping time = 5 seconds
  - · the number of times = once
  - use of R-type flux
- (2) Use of Sn-3.0Ag-0.5Cu solder Bath
  - · solder bath temperature = 245°C
  - · dipping time = 5 seconds
  - · the number of times = once
  - · use of R-type flux

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